MAX solutions

Mill-Max Expands its Line of Receptacles with *Organic Fibre Plug®*Solder Barrier -- 14 Styles Offered, Tape & Reel Packaged

Mill-Max's organic fibre plug (OFP®) solder barrier receptacles are discrete sockets for through-hole soldering into printed circuit boards. These open bottom receptacles are fitted with organic fibre plugs to prevent solder, paste or flux from contaminating the internal contact during the placing and soldering process. When the device/mating lead is plugged into the receptacle the OFP® is knocked out allowing the mating lead to pass through the fingers of the internal contact and make a reliable electrical connection.

14 sizes/styles are now available, 13 have standard tape & reel packaging. The advantage of tape & reel packaging for these receptacles is it permits through-



hole components to be placed simultaneously with surface mount parts on pick-'n-place assembly lines – eliminating the need to hand place the receptacles in an additional manufacturing step. The OFP® barrier permits the sockets to be vacuum picked from the tape prior to placement in a hole in the circuit board.

The knock-out-bottom feature enables these sockets to be made relatively short compared to many similar receptacles. The reduced length provides two advantages: the receptacles can stand upright and stable in a carrier tape pocket and the protrusion through the PCB is minimal — especially important when working with SMT boards. The open bottom receptacle design eliminates the need to trim long device leads that would otherwise bottom out in a closed receptacle design and also makes them ideal for low profile board stacking applications via the ability to pass through.

The OFP® parts are available as discrete receptacles and can be supplied in bulk or on carrier tape per EIA-481 for industry standard pick and place machines.

All Mill-Max receptacles use a precision-machined brass housing with a press-fit beryllium copper "multi-finger" contact.

(Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The receptacles are placed into plated-through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated-through-holes and achieve solder joints as reliable as wave soldering. The OFP® barrier prevents solder paste from being picked-up inside the contact during pick 'n place assembly. "Overprinting" paste on the solder mask can be used to adjust the volume of paste required to fill each hole.)

Visit www.mill-max.com/PR626 for more information.

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PIN RECEPTACLES With Organic Fibre Plug[®] Solder Barrier (see specific contact range on pages 216, 217 & 219)



- These through-hole (tubular) receptacles are designed for hand, wave or reflow* soldering. The ORGANIC FIBRE PLUG® barrier prevents solder, paste or flux from contaminating the spring contact.
- After soldering, the *OFP*[®] barrier is pushed out of the receptacle when the device is plugged in.
- All parts are available as discrete receptacles; but for SMT assembly, certain receptacles are supplied on carrier tape per EIA-481 to feed industry standard pick and place machines.

*Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The receptacles are placed into plated through-holes in the circuit board (solder paste has previous-



ly been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated through-holes and achieve solder joints as reliable as wave soldering. The OFP® barrier prevents solder paste from being picked-up inside the contact during pick in place assembly. "Overprinting" paste on the solder mask can be used to adjust the volume of paste required to fill each hole.

4015 0577 *5359* .058 DIA .048 DIA .020 .010 .025 .052 DIA .038 DIA .086 .089 .100 .060 .040 DIA 100 .028 DIA .031 DIA .043 DIA .009 .009 009 5359-0-XX-XX-10-XX-10-0 0577-0-XX-XX-21-XX-10-0 4015-0-XX-XX-30-XX-10-0 Solder mount in Ø.043±.003 PTH. Solder mount in Ø.045±.003 PTH. Solder mount in Ø.057±.003 PTH. #10 Contact for Ø.012-.017 pins. #21 Contact for Ø.015-.022 pins. #30 Contact for Ø.015-.025 pins. Also available on 16mm wide carrier Also available on 12mm wide carrier Also available on 8mm wide carrier tape: 3,000 parts per 13" reel. tape: 3,000 parts per 13" reel. tape: 5,500 parts per 13" reel. ORDER CODE: XXXX - 0 - XX - XX - XX - XX - XX - 0 **SPECIFICATIONS** SHELL MATERIAL: Brass Alloy 360, 1/2 Hard BASIC PART # -CONTACT MATERIAL: SPECIFY PACKAGING: SPECIFY CONTACT FINISH: Beryllium Copper Alloy 172, HT 43 Discrete Receptacles ♦ 27 30μ" GOLD OVER NICKEL (RoHS) SOLDER BARRIER: Organic Fibre Plug® 67 Supplied on 13" Reels 02 100μ" TIN/LEAD OVER NICKEL DIMENSION IN INCHES SPECIFY SHELL FINISH: ♦ 84 100µ" TIN OVER NICKEL (RoHS) TOLERANCES ON: 01 200μ" TIN/LEAD OVER NICKEL LENGTHS: ±.005 ♦ 80 200µ" TIN OVER NICKEL (RoHS) CONTACT DIAMETERS: ±.002 #10, #21 or #30 CONTACT (DATA ON PAGES 216, 217 & 219) ANGLES:



PIN RECEPTACLES

With Organic Fibre Plug[®] Solder Barrier (see specific contact range on pages 220 - 228)

